ABSTRACT

The present disclosure provides an electrical connection structure, a lower electrode assembly, and a process chamber. The disclosed electrical connection structure is for a wafer carrying apparatus. The electrical connection structure includes an insulating base and a conductive part, where: the conductive part is configured to supply power to the wafer carrying apparatus, the conductive part includes a first rigid conductive member, a deformable conductive member, and a second rigid conductive member that are connected in sequence, the first rigid conductive member and the second rigid conductive member extend through the insulating base, the insulating base has a deformation space, and the deformable conductive member is disposed in the deformation space. The above solution can solve the problem that the wafer carrying apparatus in the related art is prone to damage.